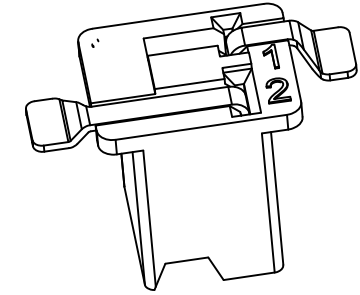
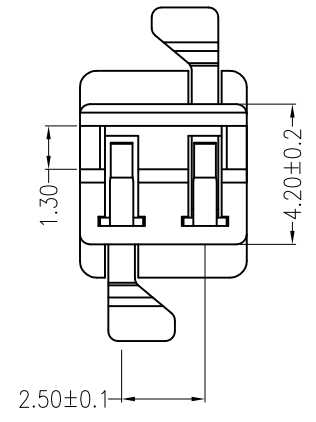
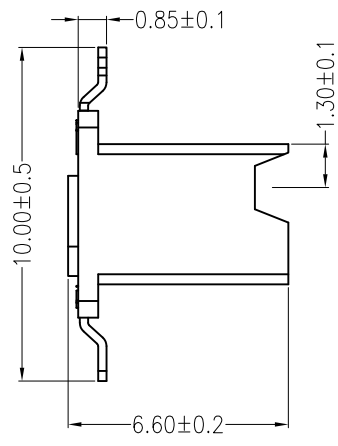
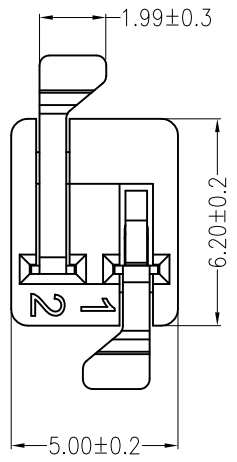
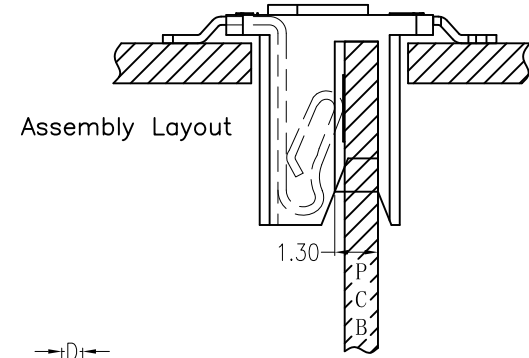


REV	DESCRIPTION	DESIGN	DATE
A0	Release	吴丹平	2016.04.30
A1	Add circuit board diagram	Jiangjianyin	2020.07.25

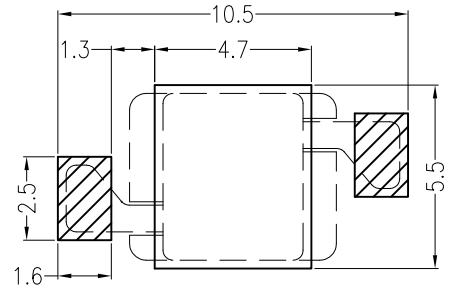
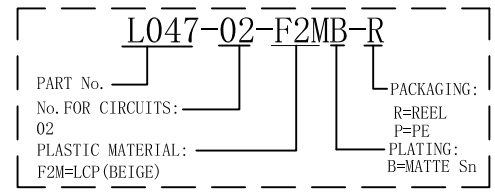


主要技术参数 Main Specifications

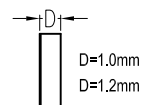
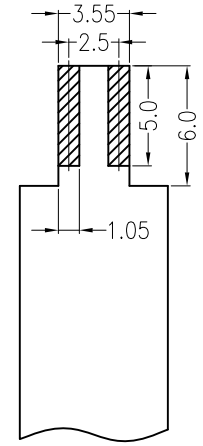
板厚 (thickness): 1.0mm
 接触电阻 (Contact resistance): $\leq 20m\Omega$
 绝缘电阻 (Insulation resistance): $\geq 1000M\Omega$
 额定电压 (Rated voltage): 250V AC DC
 额定电流 (Rated current): 1.0A AC DC
 耐电压 (Withstand Voltage): 1000V AC/minute
 温度范围 (Temperature Range): $-40^{\circ}C \sim +120^{\circ}C$



ORDER INFORMATION:



Board Layout



Circuit board

ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
C				
B	CONTACT	2 PCS	PhosphorBronze	MATTE Sn-plated
A	PEDESTAL	1 PCS	LCP	UL 94V-0, COLOR:BEIGE

广东科斯达电子科技有限公司 GUANG DONG KE SI DA ELECTRONIC TECHNOLOGY CO., LTD.		TITLE: - 2.5mmPITCH 180°WAFER SMT TYPE	
X.±0.5	X.±5'	USE: CUSTOMER	PART NO.:
.X±0.3	.X±2'		L047-02-F2MB-R
.XX±0.25	.XX±1'	APPD: 王锋	DWG NO.:
--	--	CHKD: 曾令青	GCCP-0076
UNITS: mm	DR: 蒋建银	SCALE	SHEET
		1 : 1	1 / 1